

Title (en)
Copper-based sliding material

Title (de)
Gleitmaterial auf Kupferbasis

Title (fr)
Matériau coulissant à base de cuivre

Publication
EP 2135964 B1 20140312 (EN)

Application
EP 09008100 A 20090619

Priority
JP 2008161635 A 20080620

Abstract (en)
[origin: EP2135964A2] A copper-based sliding material consisting of: 5.0 to 25.0 mass % of Zn; 4.2 to 10.0 mass % of Bi; 2.0 to 7.0 mass % of Mn; 1.0 to 3.0 mass % of Si; 0.1 to 2.0 mass % of Sn; and the balance being Cu and unavoidable impurities is provided. The copper-based sliding material includes a single \pm -phase matrix (1, 2), a Mn-Si compound (3) and a Bi-particle phase (4). The Mn-Si compound (3) and the Bi-particle phase (4) are dispersed in the single \pm -phase matrix (1, 2). The mass ratio of Sn to Bi is 0.024 to 0.200, preferably 0.050 to 0.140.

IPC 8 full level
C22C 9/04 (2006.01)

CPC (source: EP)
C22C 9/04 (2013.01)

Cited by
RU2732139C2; GB2489609A; GB2489609B; US11359263B2; WO2017198698A1; US11427890B2; US8790574B2; US10570484B2

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

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